

Final Product Change Notification

201811004F01

Issue Date: 31-Dec-2018

Effective Date: 15-Apr-2019

Here's your personalized quality information concerning products Digi-Key purchased from Nexperia.
For detailed information we invite you to view this notification online



Management Summary

Change the die of the PBSSx350Z to the known 1160x810µm² pitch with glue back metal.

Change Category

- | | | | | |
|---|--|--|---|---|
| <input checked="" type="checkbox"/> Wafer Fab Process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input checked="" type="checkbox"/> Design |
| <input checked="" type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

Change of die size and attach technology for PBSSx350Z

Details of this Change

Change die attach from eutectic to glue die attach and shrink of die size for 50 V, 3 A BISS transistors in SOT223. Additionally PBSS5350Z will be released to use 8 inch wafer diameter.

Why do we Implement this Change

To increase flexibility and volume ramp-up.

Identification of Affected Products

The products using a chip from a 8 inch wafer can be identified by a marker on the die surface.
Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 31-Jan-2019

Production

Planned first shipment 15-Apr-2019

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
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201509006F02	08-Dec-2015	21-Mar-2016	Change of bond wire from Au to Cu for transistors in SOT223 package
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Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 30-Jan-2019. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

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Affected Part Numbers

PBSS4350Z,135

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